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FQP50N06

60V N-Channel MOSFET

General Description

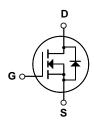
These N-Channel enhancement mode power field effect transistors are produced using Fairchild's proprietary, planar stripe, DMOS technology.

This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for low voltage applications such as automotive, DC/ DC converters, and high efficiency switching for power management in portable and battery operated products.

Features

- 50A, 60V, $R_{DS(on)}$ = 0.022 Ω @V_{GS} = 10 V Low gate charge (typical 31 nC)
- Low Crss (typical 65 pF)
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability
- 175°C maximum junction temperature rating





Absolute Maximum Ratings T_C = 25°C unless otherwise noted

Symbol	Parameter		FQP50N06	Units
V _{DSS}	Drain-Source Voltage		60	V
I _D	Drain Current - Continuous (T _C = 25°C)		50	А
	- Continuous (T _C = 100°C)		35.4	А
I _{DM}	Drain Current - Pulsed	(Note 1)	200	А
V _{GSS}	Gate-Source Voltage		± 25	V
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	490	mJ
I _{AR}	Avalanche Current	(Note 1)	50	А
E _{AR}	Repetitive Avalanche Energy	(Note 1)	12	mJ
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	7.0	V/ns
P_{D}	Power Dissipation (T _C = 25°C)		120	W
	- Derate above 25°C		0.8	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +175	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds		300	°C

Thermal Characteristics

Symbol	Parameter	Тур	Max	Units
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case		1.24	°C/W
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink	0.5		°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient		62.5	°C/W

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Cha	aracteristics					
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V, } I_D = 250 \mu\text{A}$	60			V
ΔBV _{DSS} / ΔΤ _J	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to 25°	С	0.06		V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 60 V, V _{GS} = 0 V			1	μΑ
		V _{DS} = 48 V, T _C = 150°C			10	μΑ
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 25 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage Current, Reverse	$V_{GS} = -25 \text{ V}, V_{DS} = 0 \text{ V}$			-100	nA
On Cha	racteristics					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		4.0	V
R _{DS(on)}	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_D = 25 \text{ A}$		0.018	0.022	Ω
g _{FS}	Forward Transconductance	V _{DS} = 25 V, I _D = 25 A (Note	1)	22		S
C _{iss} C _{oss}	Input Capacitance Output Capacitance Reverse Transfer Capacitance	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V},$ f = 1.0 MHz		1180 440 65	1540 580 90	pF pF
	,			03	90	рі
	Ing Characteristics Turn-On Delay Time			15	40	no
t _{d(on)} t _r	Turn-On Rise Time	$V_{DD} = 30 \text{ V}, I_{D} = 25 \text{ A},$		105	220	ns ns
	Turn-Off Delay Time	$R_G = 25 \Omega$		60	130	ns
t _{d(off)}	Turn-Off Fall Time	(Note 4,		65	140	ns
Q _g	Total Gate Charge	V _{DS} = 48 V, I _D = 50 A,		31	41	nC
Q _{gs}	Gate-Source Charge	$V_{DS} = 46 \text{ V}, I_D = 50 \text{ A},$ $V_{GS} = 10 \text{ V}$		8		nC
Q _{gd}	Gate-Drain Charge	(Note 4,	5)	13		nC
	J					
Drain-S	ource Diode Characteristics a	nd Maximum Ratings				
I _S	Maximum Continuous Drain-Source Diode Forward Current				50	Α
I _{SM}	Maximum Pulsed Drain-Source Diode F				200	Α
V_{SD}	Drain-Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_{S} = 50 \text{ A}$			1.5	V
t _{rr}	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, I_S = 50 \text{ A},$		52		ns
Q_{rr}	Reverse Recovery Charge	$dI_F / dt = 100 A/\mu s$ (Note 4)		75		nC

- **Notes:**1. Repetitive Rating : Pulse width limited by maximum junction temperature 2. L = 230μH, I_{AS} = 50A, V_{DD} = 25V, R_G = 25 Ω, Starting T_J = 25°C 3. lg_D = 50A, di/dt \leq 300A/μs, V_{DD} \leq BV_{DSS}, Starting T_J = 25°C 4. Pulse Test : Pulse width \leq 300μs, Duty cycle \leq 2% 5. Essentially independent of operating temperature

Typical Characteristics

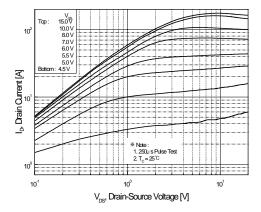


Figure 1. On-Region Characteristics

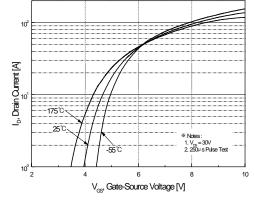


Figure 2. Transfer Characteristics

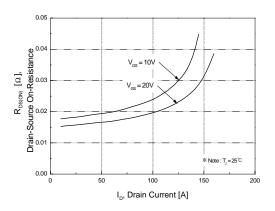


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

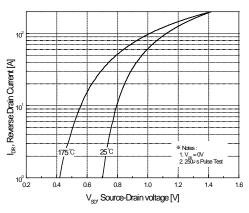


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

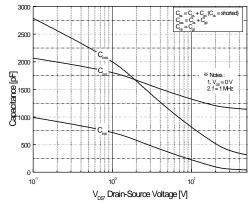


Figure 5. Capacitance Characteristics

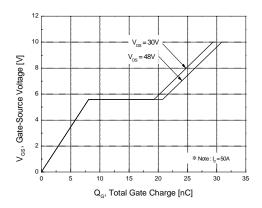
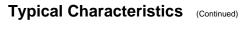


Figure 6. Gate Charge Characteristics



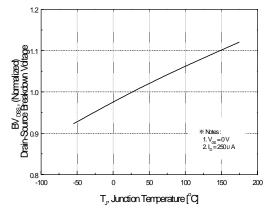


Figure 7. Breakdown Voltage Variation vs. Temperature

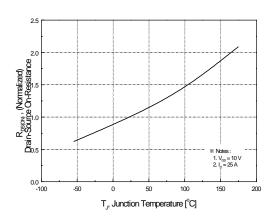


Figure 8. On-Resistance Variation vs. Temperature

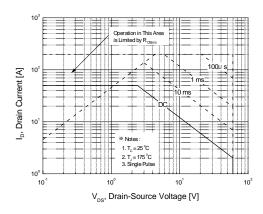


Figure 9. Maximum Safe Operating Area

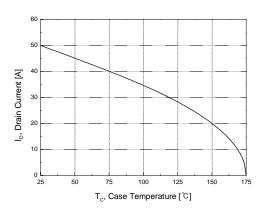


Figure 10. Maximum Drain Current vs. Case Temperature

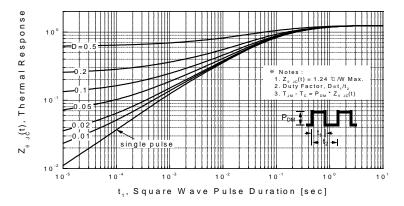
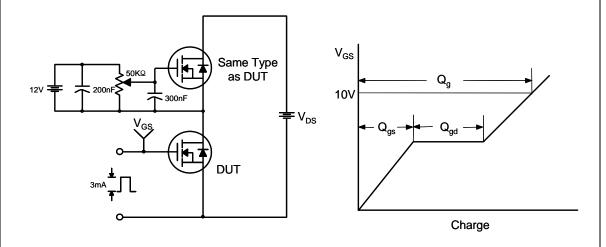


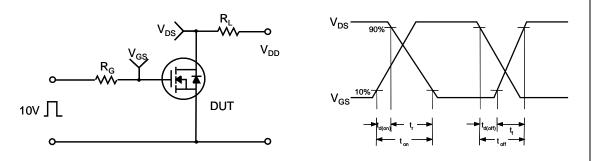
Figure 11. Transient Thermal Response Curve

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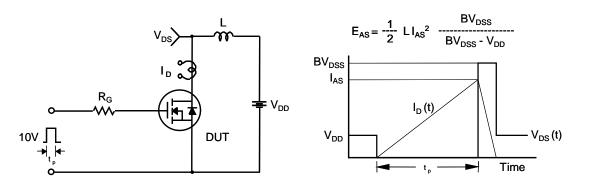
Gate Charge Test Circuit & Waveform



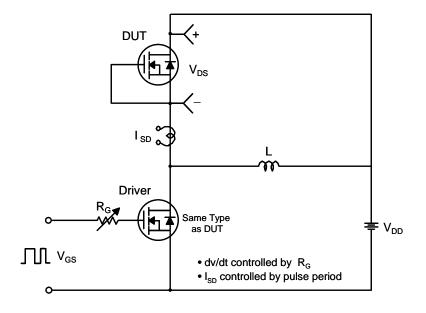
Resistive Switching Test Circuit & Waveforms



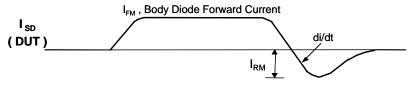
Unclamped Inductive Switching Test Circuit & Waveforms



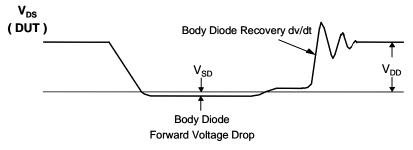
Peak Diode Recovery dv/dt Test Circuit & Waveforms

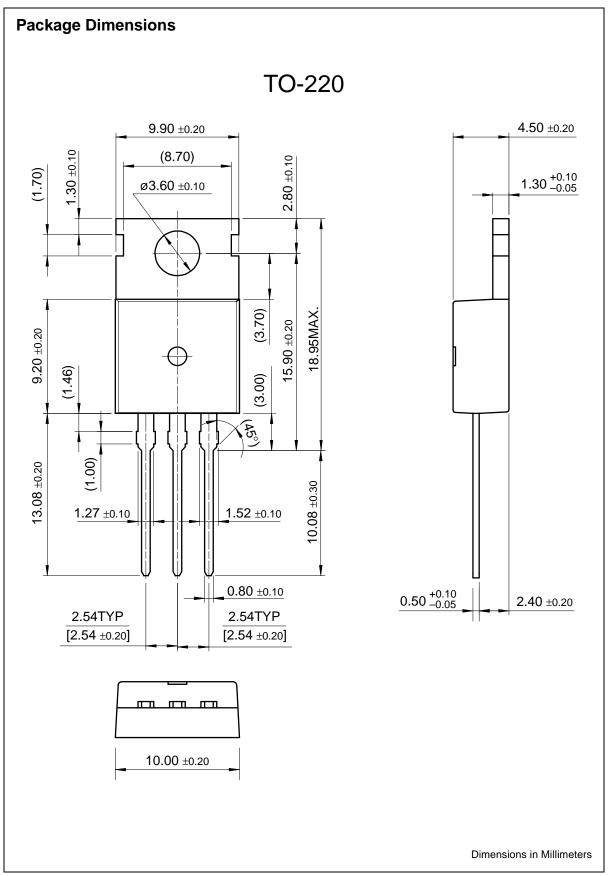






Body Diode Reverse Current





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